

Macromodels of IC Buffers Allowing for Large Power Supply Fluctuations

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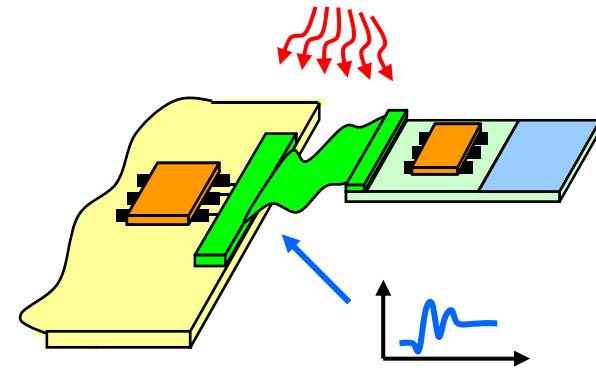
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<http://www.emc.polito.it/>



Introduction

Models of IC buffers required for the system-level assessment of **signal integrity** and **EMC** effects via numerical simulation

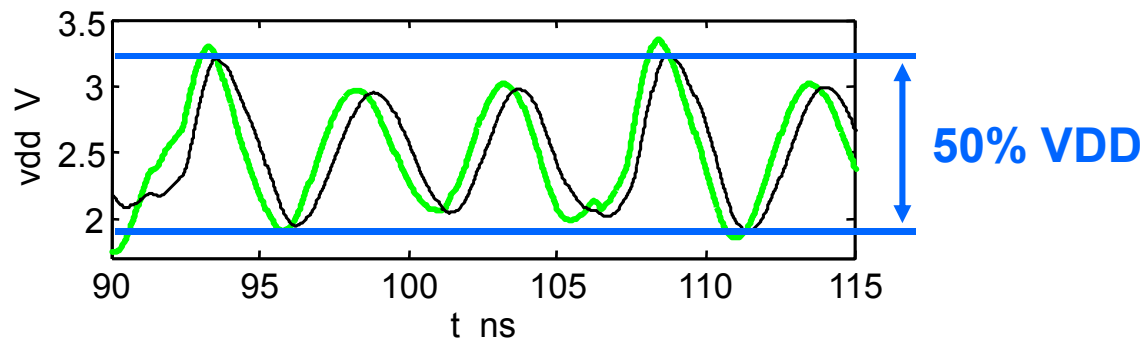
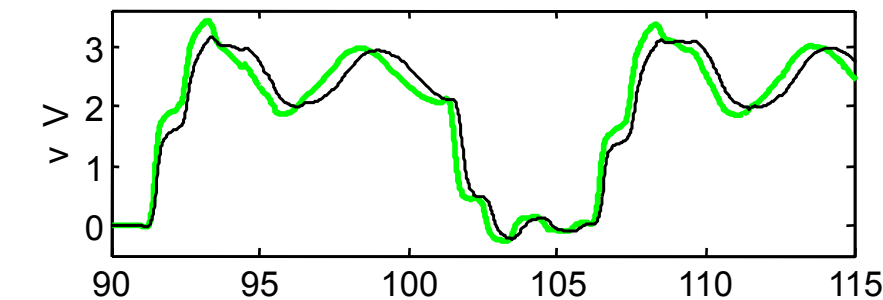


Include the effects of power supply variations

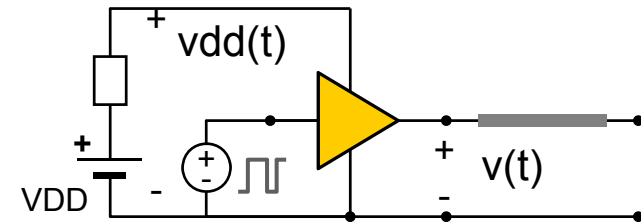
- ❑ **Recent applications** (e.g., stacked SiP devices, → memories) exhibit large variation (30÷40%)
- ❑ **State-of-the art models allow only for limited variations** (10÷15% of the nominal power supply voltage)

Improve existing models

Example



— reference — $M\pi\log$ model [1]



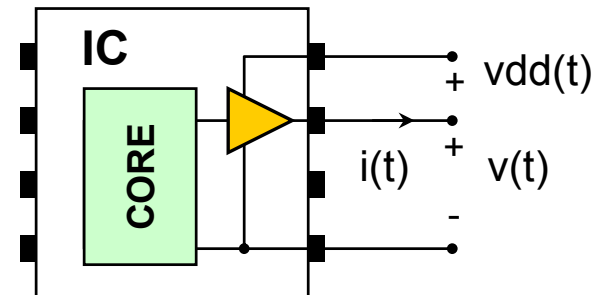
**Waveform distortion
produced by the
state-of-the-art models**

**Where do these
differences come from?**

[1] I.S.Stievano et. Al., "M[pi]log, Macromodeling via parametric identification of logic gates", TADVP 2004.

Mπlog model structure

e.g., IC output buffer (single-ended)



□ 2-piece model representation

$$i(t) = w_H(v, v_{dd}, t) i_H(v, v_{dd}, d/dt) + w_L(v, v_{dd}, t) i_L(v, v_{dd}, d/dt)$$

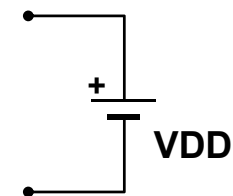
$i_{H,L}$: submodels accounting for buffer behavior @ fixed logic H and L state
 $w_{H,L}$: weighting signals for state switchings

□ Underlying (simplifying) assumptions

Model parameters computed for the **nominal power supply VDD**

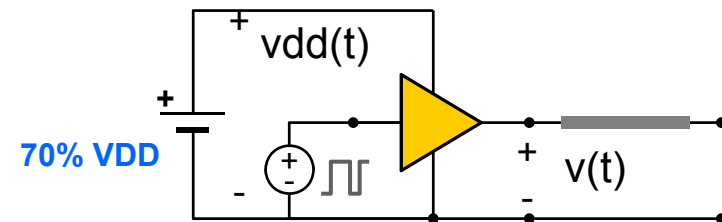
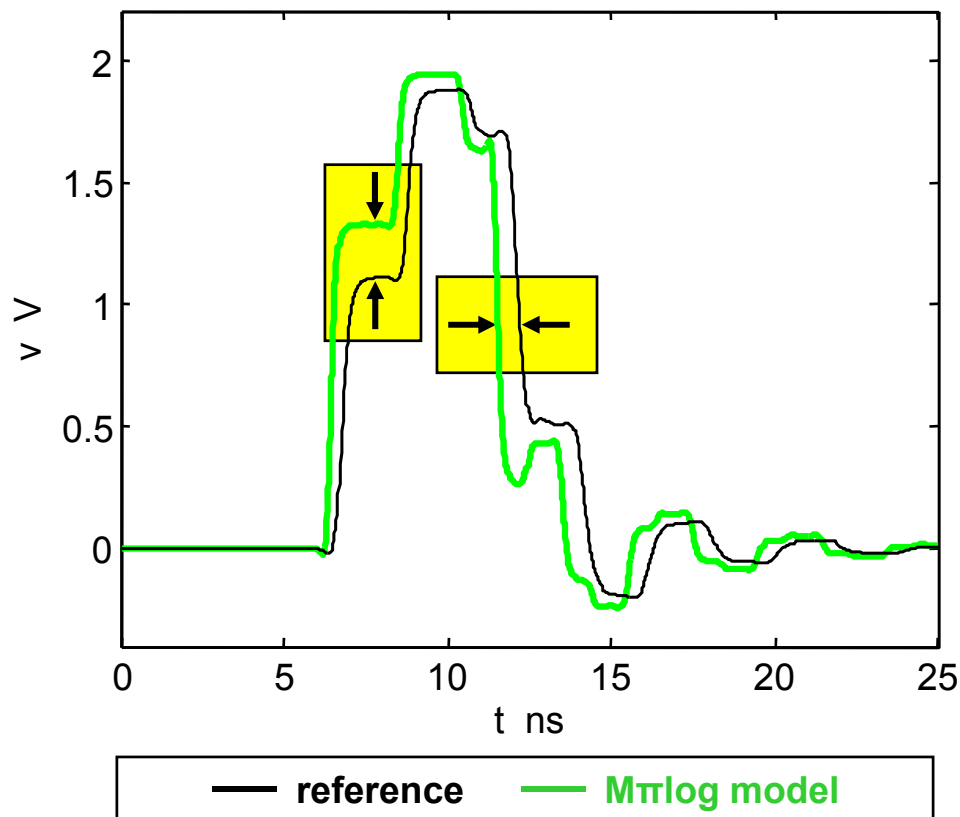
Weighting signals $\rightarrow w_{H,L}(t)$

Submodels $i_{H,L} \rightarrow i_H = i_H(v_{dd}-v, d/dt)$, $i_L = i_L(v, d/dt)$



M π log model structure, cont'd

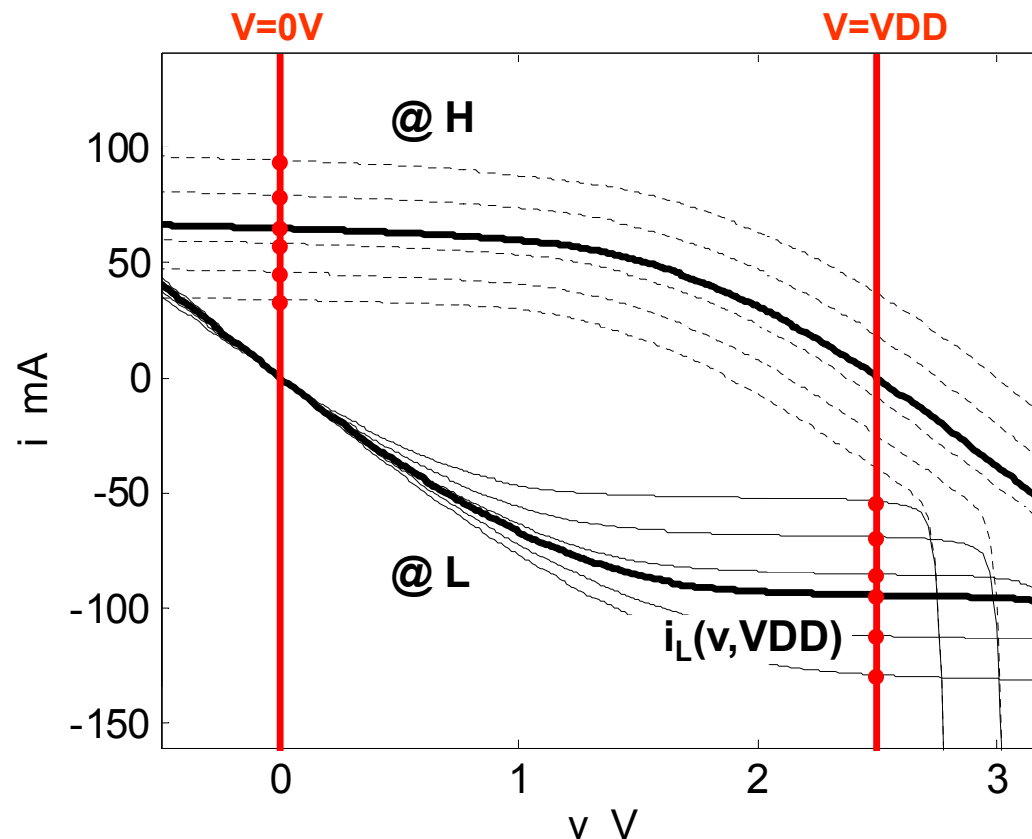
☐ Ideal power supply @ 70% VDD



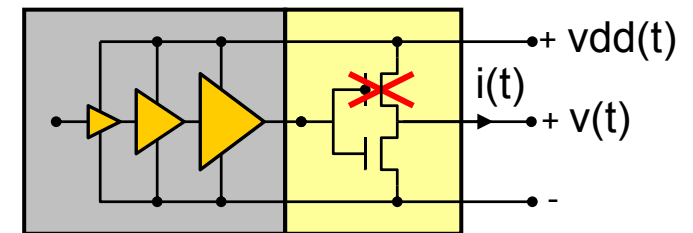
- ☐ Static error
- ☐ Timing error (delay)

A – static compensation

□ Static surface for $v_{dd} \in [70,130]\%VDD$



e.g., Device @ L state

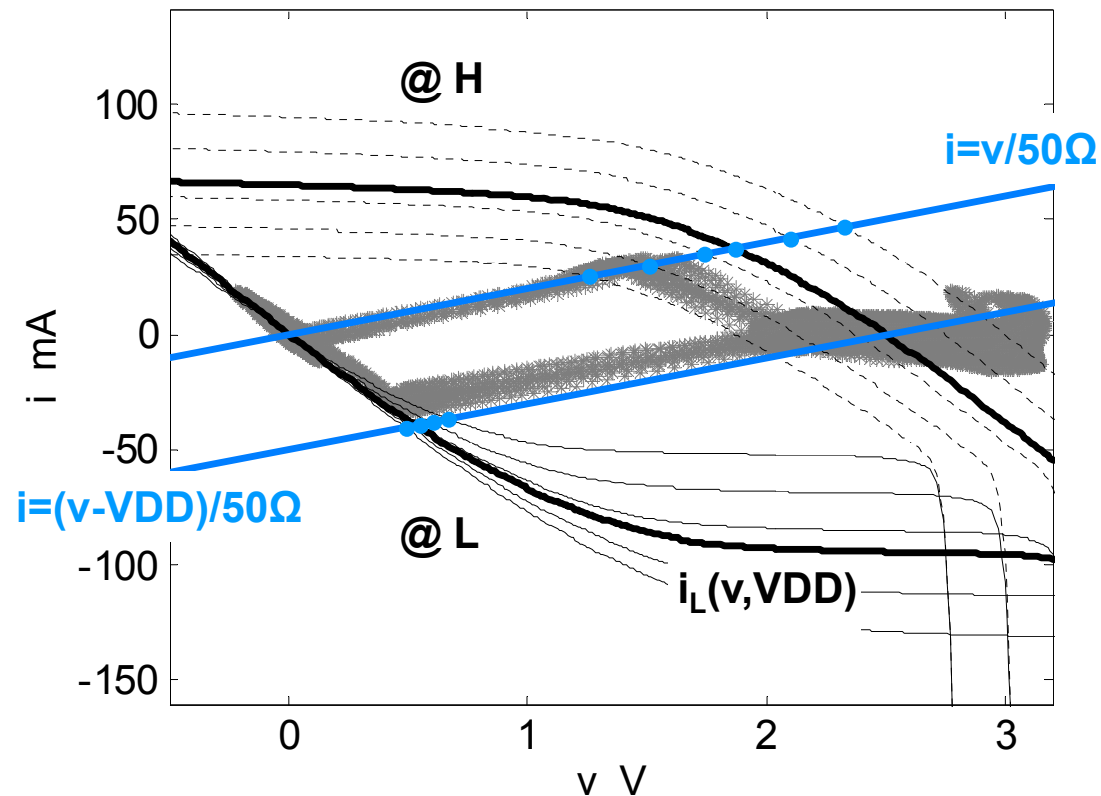


- State-of-the-art: $i_L(v, VDD)$ (—)
- Complete 2D surface (**model complexity increases**)
- $i_L(v, v_{dd}) = k_L(v_{dd}) * i_L(v, VDD)$ [2]

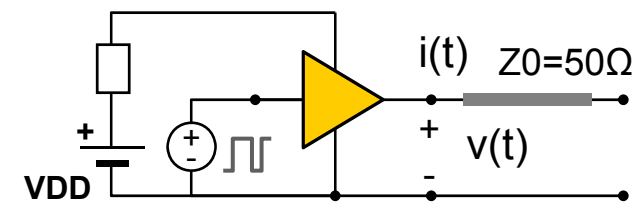
[2] Arpad Muranyi et. Al., "Gate Modulation Effect (table format)," IBIS BIRD #98.1, May 20, 2005.

A – static compensation, cont'd

□ Static surface for $v_{dd} \in [70,130]\%VDD$



▪ Actual i-v operating region



▪ Proposed model

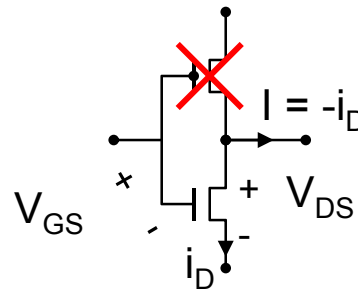
$$i_L(v, v_{dd}) = k_L(v_{dd}) * i_L(v, VDD)$$

↑
computed along
the TL load lines

A – static compensation, cont'd

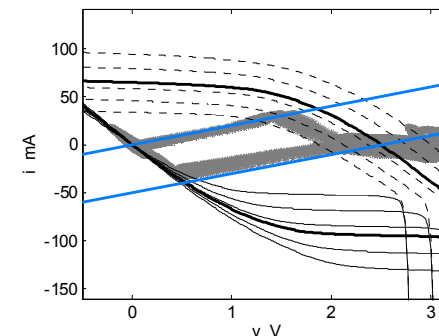
$$i_L(v, v_{dd}) = k_L(v_{dd}) * i_L(v, V_{DD})$$

- ❑ include the information of the analytical MOS equations
- ❑ triode region [3]



$$i_D \cong A_n (V_{GS} V_{DS} - V_{DS}^2/2)$$

- A_n fitted with $i_L(v, V_{DD})$ (—)
- $k_L(v_{dd})$ by matching analytical NMOS equation with model equation along the **load lines**

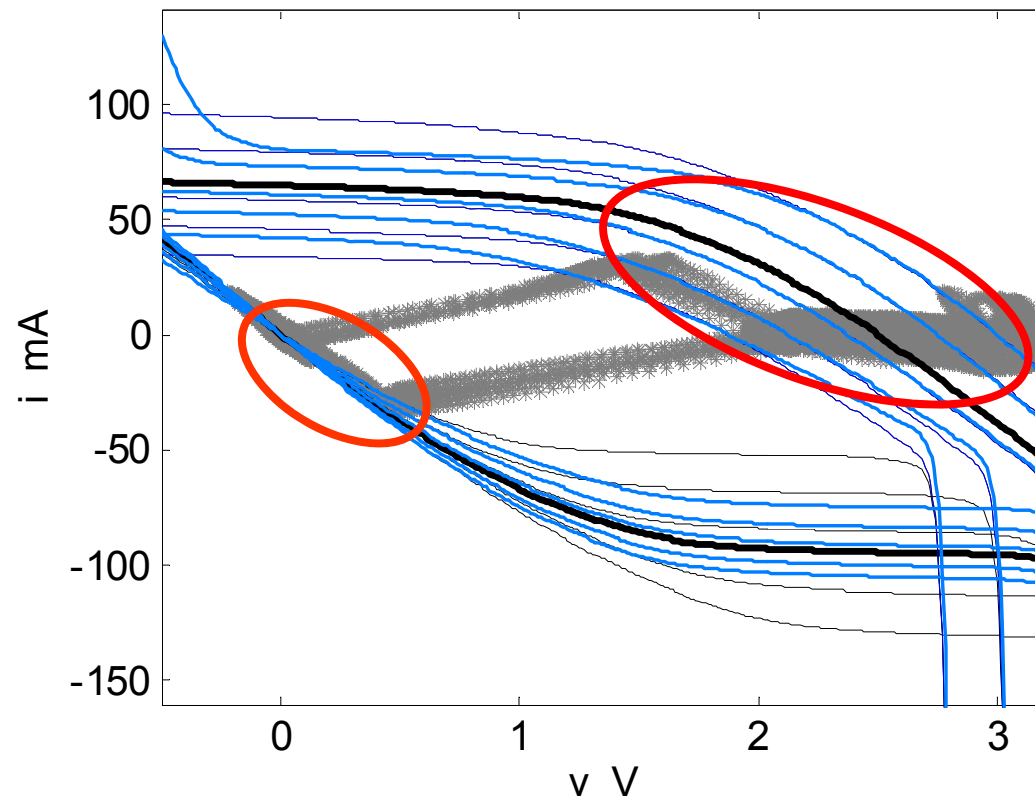


- ❑ **Need of static characteristics @ VDD only (—)**

[3] Jan M. Rabaey, "Digital Integrated Circuits - 2nd ed.", Prentice Hall electronics and VLSI series, 2003

A – static compensation, cont'd

□ DC model response



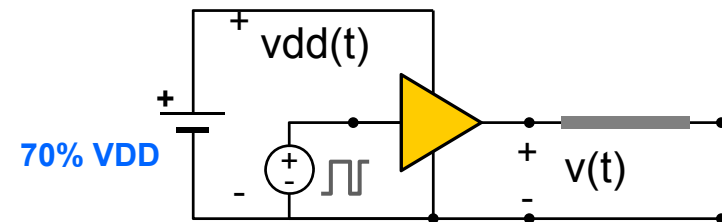
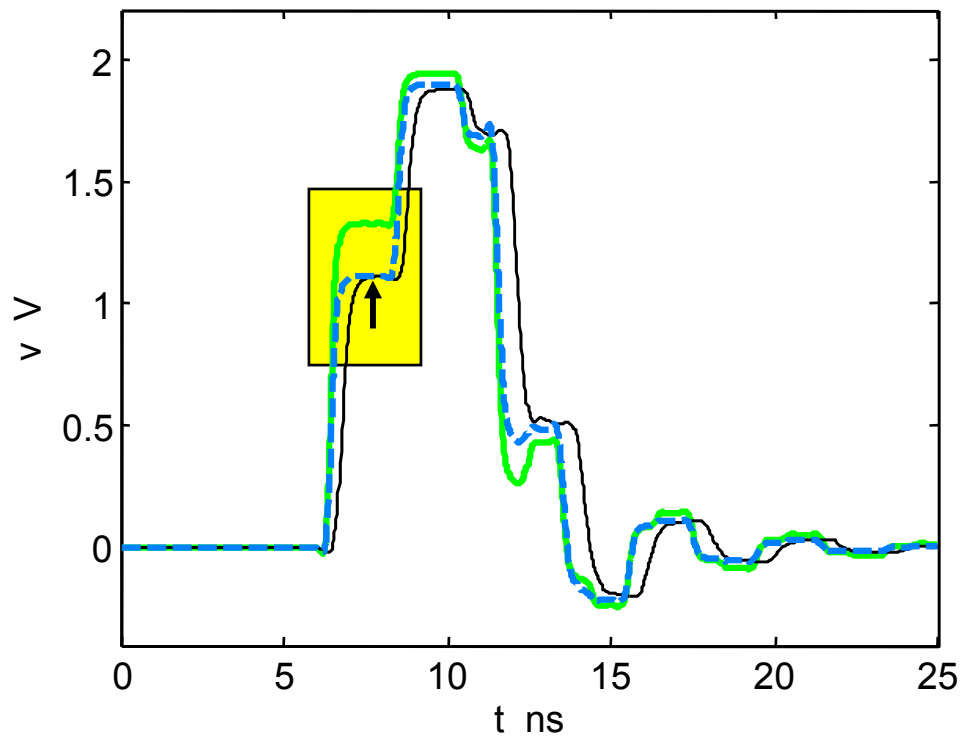
Relative errors less than 2%

**Possible discrepancies
outside the operating region
do not affect model accuracy**

— reference — enhanced model
(static comp.)

A – static compensation, cont'd

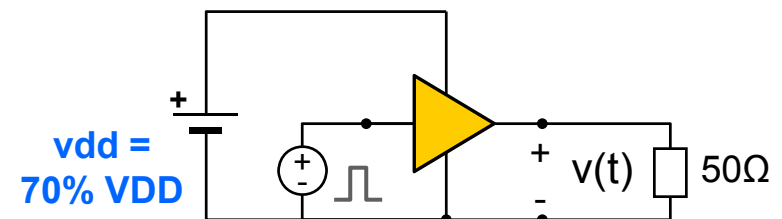
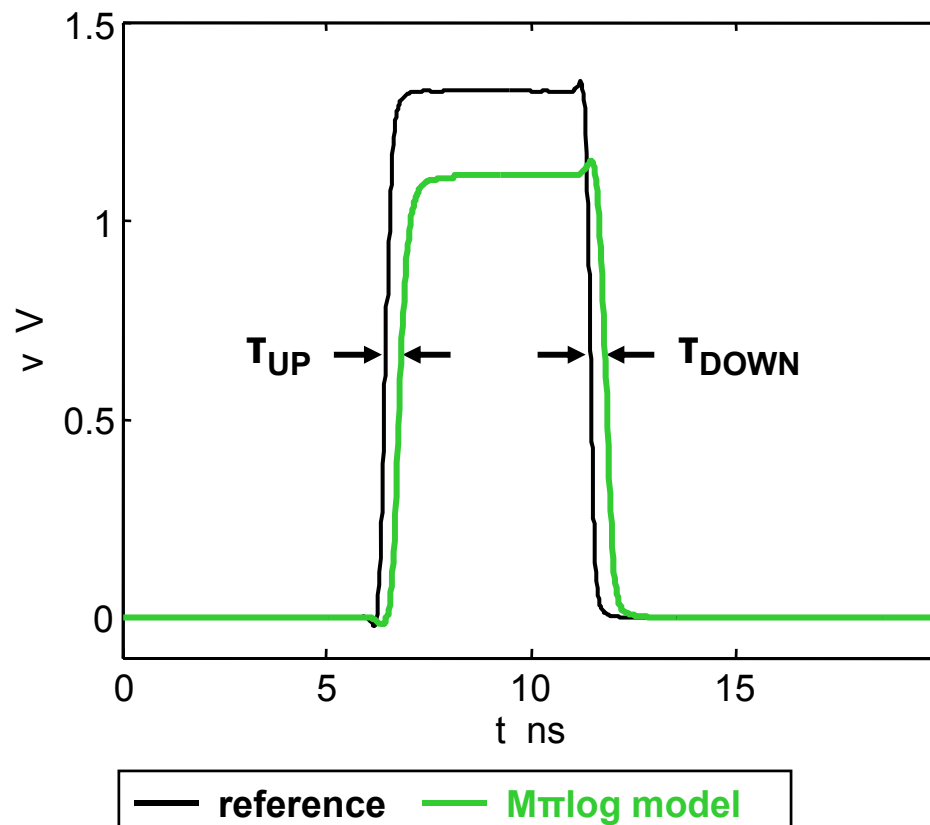
□ Ideal power supply @ 70% VDD



— reference — M π log model
— enhanced model (static comp.)

**Accurate prediction even
with a very simple
approximation of the 2D
static surface**

B – delay compensation

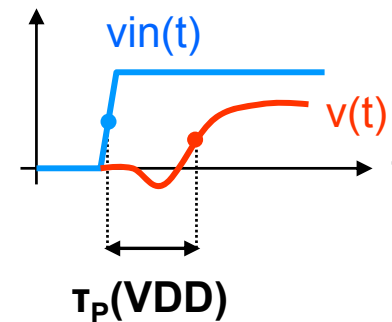
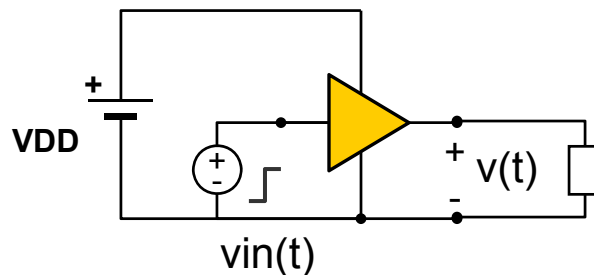


- ❑ Embed the τ (UP,DOWN) information in the model

$$w_{H,L}(t) \rightarrow w_{H,L}(t - \tau(v_{dd}))$$

B – delay compensation, cont'd

□ Delay propagation [3]



$$\tau_P(vdd) \cong \tau_P(VDD) * (VDD/vdd) \quad (\text{accuracy: } \sim 5\%)$$

$$w_{H,L}(t) = w_{H,L}(t - \tau(vdd))$$

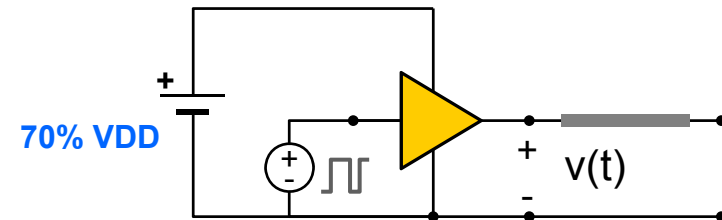
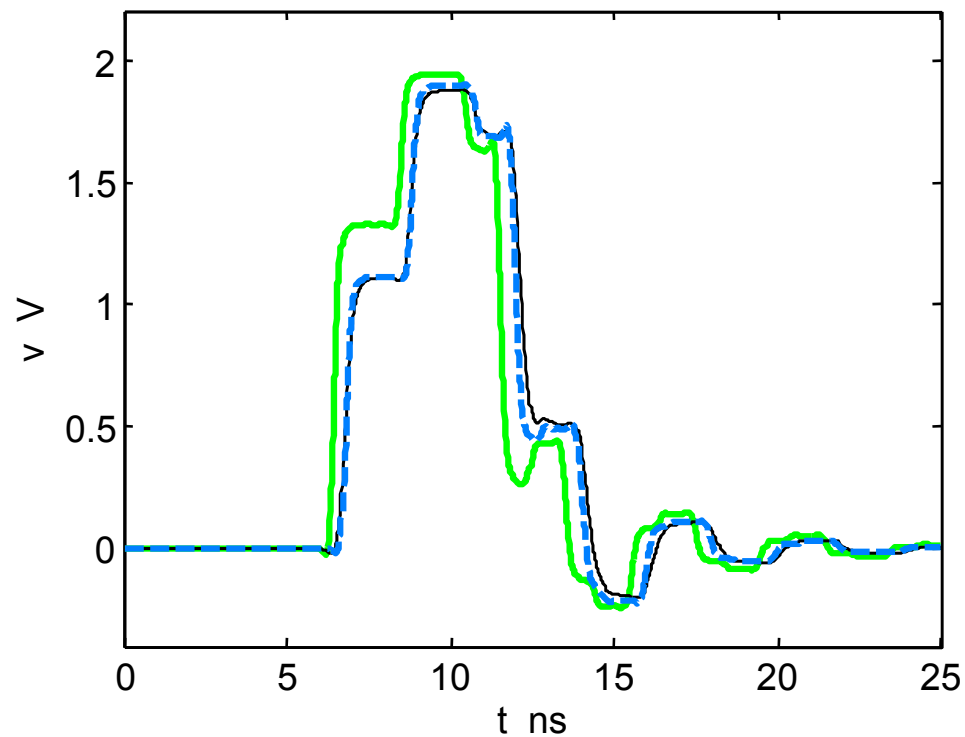
$$\tau(vdd) = \tau_P(VDD) - \tau_P(vdd) = \tau_P * (1 - VDD/vdd)$$

**No additional
information
is required**

[3] Jan M. Rabaey, "Digital Integrated Circuits - 2nd ed.", Prentice Hall electronics and VLSI series, 2003

Enhanced model performance

□ Ideal power supply @ 70% VDD

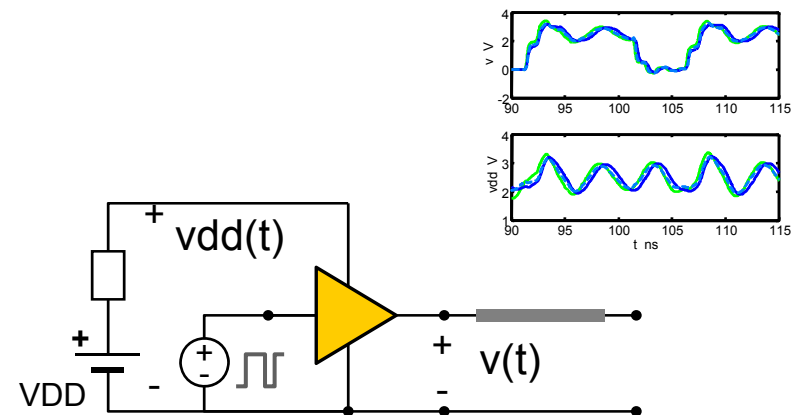
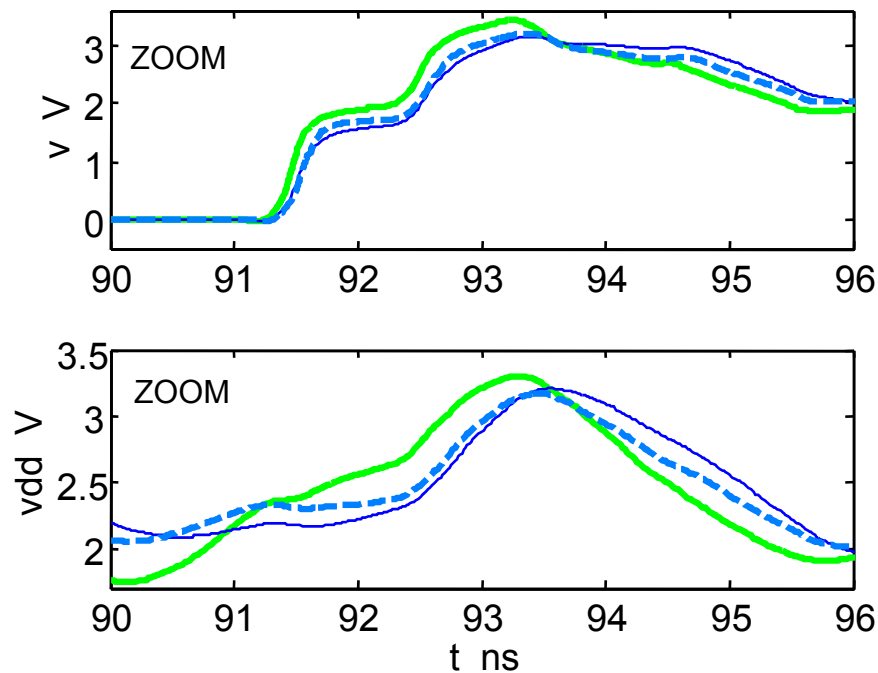


— reference — $M\pi\log$ model
 — enhanced model (static & delay comp.)

Good accuracy
Same results for 130% VDD

Enhanced model performance, cont'd

Realistic test



— reference — Mπlog model
 — enhanced model (static & delay comp.)

**Accuracy confirmed for
 $v_{dd}(t) > 40\% V_{DD}$**

Current vs. enhanced models

$$i(t) = w_H(v, v_{dd}, t) i_H(v, v_{dd}, d/dt) + w_L(v, v_{dd}, t) i_L(v, v_{dd}, d/dt)$$

Model	Submodels $i_{H,L}$	Weighting signals $w_{H,L}$
M π log	$i_{H,L}(v, \mathbf{VDD}, d/dt)$	$w_{H,L}(\mathbf{t})$
Enhanced M π log	$i_{H,L}(v, \mathbf{vdd}, d/dt)$	$w_{H,L}(\mathbf{t} - \tau(\mathbf{vdd}))$

- ❑ **no additional characterization required**
- ❑ **same complexity** → **same speed-up** (10 ÷ 100x)

Conclusions

- ❑ Generation of **enhanced device models** for large VDD variations (>30%)
- ❑ Simplified analytical equations for static & delay compensation
- ❑ **High accuracy** verified on realistic tests
- ❑ Apply to different device types (**e.g., precomp**)

MOCHA, MOdelling and CHAracterization for SiP - Signal and Power Integrity Analysis

❑ European Project FP7-ICT-2007-1 (Jan 2008 – Dec 2009)

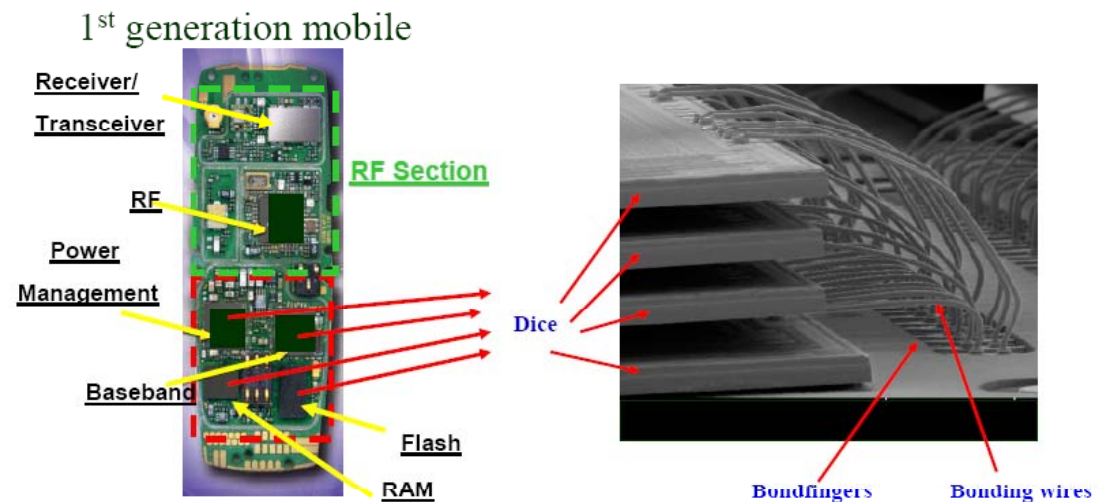
“Develop reliable modelling and simulation solutions for SiP design verification”

❑ Participants:

- **STMicroelectronics M6 SRL (Italy)**
- Politecnico di Torino (Italy)
- Cadence Design Systems GmbH (Germany)
- Agilent Technologies (Belgium)
- Universidade de Aveiro (Portugal),
- Microwave Characterization Center (France)

❑ Work Packages

- IC power integrity model
- **IC buffers' innovative modelling approach**
- SiP design and verification EDA platform
- SiP signal integrity measurement platform



Q&A

